HD74HC85

4-Bit Magnitude Comparator

HITACHI

Description

The HD74HC85 id designed for high speed comparison of two four bit words. This circuit has eight comparison input, 4 for each word; three cascade inputs (A < B, A > B, A = B); and three decision outputs (A < B, A > B, A = B). The result of a comparison is indicated by a high level on one of the decision outputs. thus it may be determined whether one word is “greater than,” “less than,” or “equal to” the other word. by connecting the outputs of the least significant stage to the cascade inputs of the enxt stage, words of greater than four bits can be compared. In addition the least significant stage must have a high level applied to the A = B input, and a low level to the A < B, and A > B inputs.

Features

- High Speed Operation: t_{pd} (Data Word Input to Output) = 20 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 µA max (Ta = 25°C)

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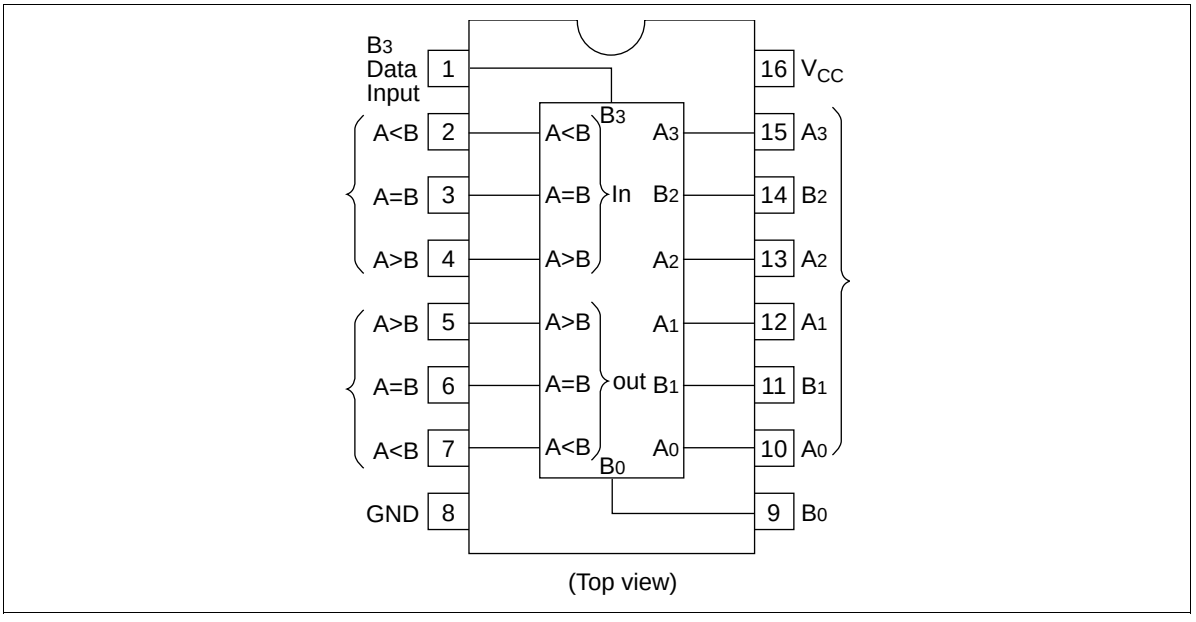
Function Table

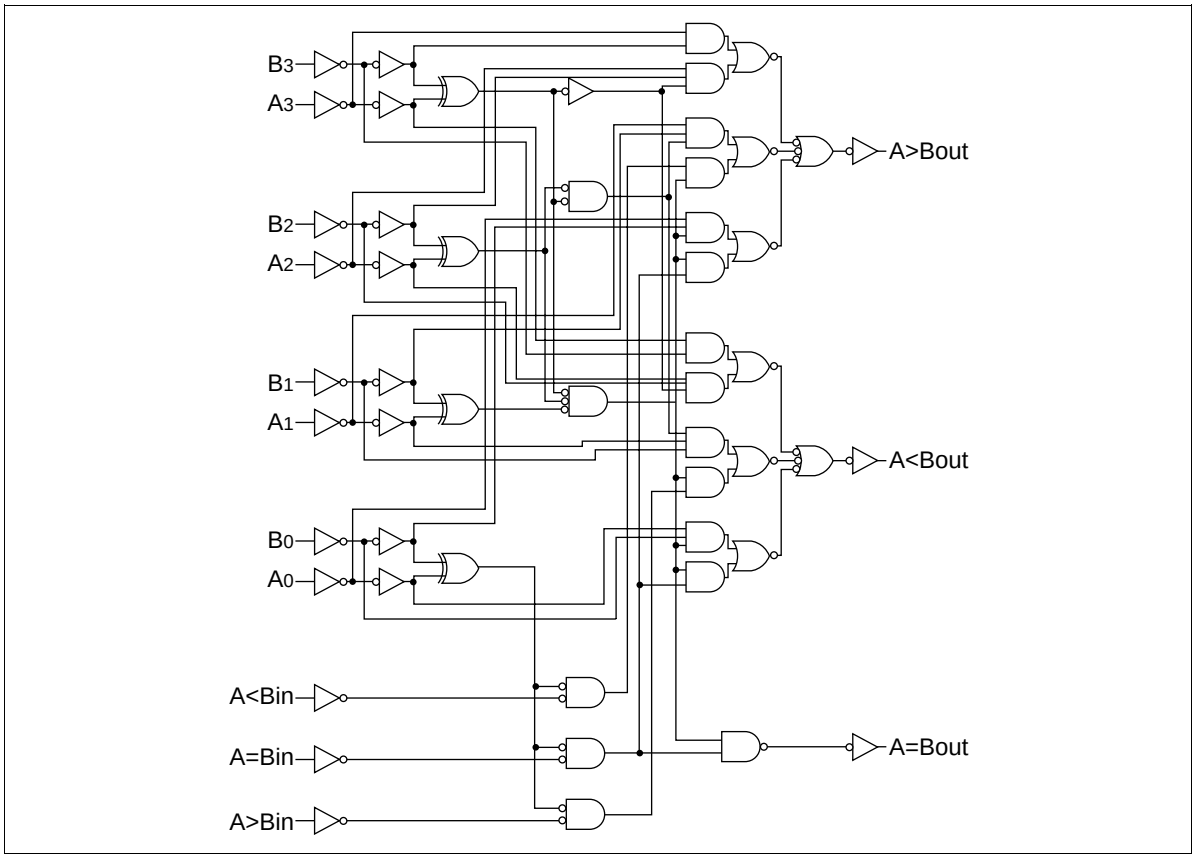
Data Word Inputs				Cascading Inputs			Outputs		
A_3, B_3	A_2, B_2	A_1, B_1	A_0, B_0	A > Bin	A = Bin	A < Bin	A > Bout	A = Bout	A < Bout
$A_3 > B_3$	X	X	X	X	X	X	H	L	L
$A_3 < B_3$	X	X	X	X	X	X	L	L	H
$A_3 = B_3$	$A_2 > B_2$	X	X	X	X	X	H	L	L
$A_3 = B_3$	$A_2 < B_2$	X	X	X	X	X	L	L	H
$A_3 = B_3$	$A_2 = B_2$	$A_1 > B_1$	X	X	X	X	H	L	L
$A_3 = B_3$	$A_2 = B_2$	$A_1 < B_1$	X	X	X	X	L	L	H
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 > B_0$	X	X	X	H	L	L
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 < B_0$	X	X	X	L	L	H
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 = B_0$	L	L	L	H	L	H
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 = B_0$	L	L	H	L	L	H
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 = B_0$	H	L	L	H	L	L
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 = B_0$	H	L	H	L	L	L
$A_3 = B_3$	$A_2 = B_2$	$A_1 = B_1$	$A_0 = B_0$	X	H	X	L	H	L

Pin Arrangement



(Top view)

Logic Diagram



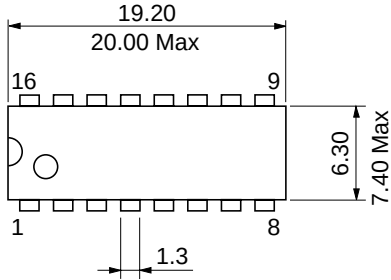
DC Characteristics

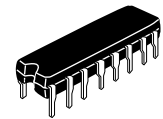
Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V_{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V_{IH} or V_{IL} I_{OH} = –20 µA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		I_{OH} = –4 mA
		6.0	5.68	—	—	5.63	—		I_{OH} = –5.2 mA
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 µA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		I_{OL} = 4 mA
		6.0	—	—	0.26	—	0.33		I_{OL} = 5.2 mA
Input current	Iin	6.0	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	µA	Vin = V_{CC} or GND, Iout = 0 µA

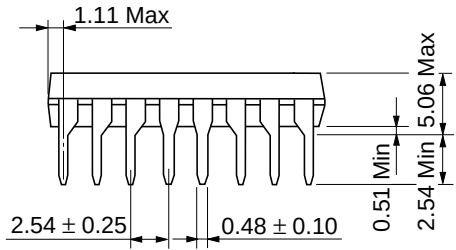
AC Characteristics (C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

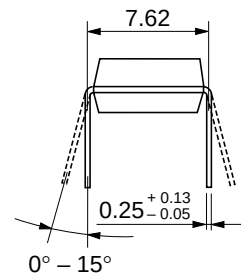
			Ta = 25°C			Ta = –40 to +85°C			
Item	**Symbol**	**V_{cc} (V)**	**Min**	**Typ**	**Max**	**Min**	**Max**	**Unit**	**Test Conditions**
Propagation delay time	t_{PLH}	2.0	—	—	210	—	265	ns	Data word input to output (Except A = Bout)
	t_{PHL}	4.5	—	20	42	—	53		
		6.0	—	—	36	—	45		
	t_{PLH}	2.0	—	—	175	—	220	ns	Data word input to A = Bout
	t_{PHL}	4.5	—	20	35	—	44		
		6.0	—	—	30	—	37		
	t_{PLH}	2.0	—	—	125	—	155	ns	A = Bin to A = Bout
	t_{PHL}	4.5	—	12	25	—	31		
		6.0	—	—	21	—	26		
	t_{PLH}	2.0	—	—	155	—	195	ns	Cascading input to output (Except A = Bout)
	t_{PHL}	4.5	—	14	31	—	39		
		6.0	—	—	26	—	33		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

Unit: mm



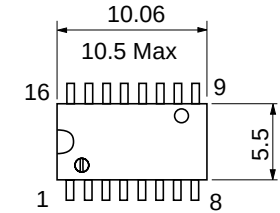


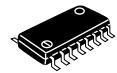


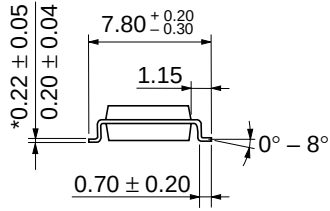


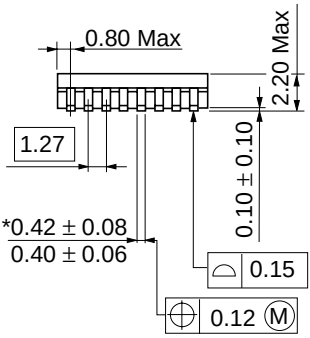
Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.07 g

Unit: mm





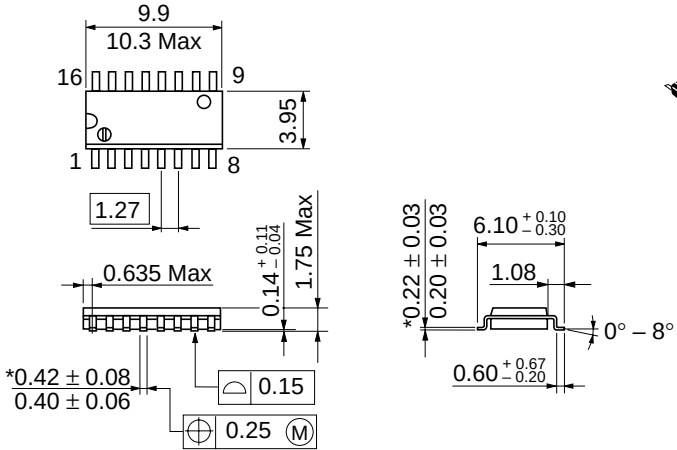


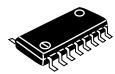


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.24 g

Unit: mm





Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

*Dimension including the plating thickness
Base material dimension

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